Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("20050121496").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 08:49
L2	2126	(FARRELL with KEVIN) or (BRADLEY with EDWIN) or (CANTER with HAL) or (KIM with GENE) or (MCCLINTOCK with DAVID) .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 08:51
L3	7	2 and (solder\$4 same (adhesive or thermoplastic or polymer\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 08:54
L5	78	(solder\$4 same ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) near10 (align\$7))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:05
L6	15	(solder\$4 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) near10 (align\$7))) and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (top or above or edge) adj4 (solder\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:22
L7	. 16	(solder\$4 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) near10 (align\$7))) and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (top or above or edge or corner) adj4 (solder\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:29
L8	2	(solder\$4 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) near10 (align\$7 or registration))) and (glue adj (ball or dot or bump))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:22
L9	5	solder\$4 and ((glue adj (ball or dot or bump)) same (reflow\$4 or melt\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:21
L11	2436	(solder\$4'and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) near10 (align\$7 or registration))) and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) with (solder\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:23
L12	1265	11 and ("228"/\$.ccls. or "29"/\$.ccls. or "156"/\$.ccls. or "438"/\$.ccls. or "257"/\$.ccls. or "174"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/07/06 09:25

L13	121	11 and ("228"/\$.cds.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:25
L14	. 111	solder\$4 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (hold\$4 or maintain\$4) adj7 (reflow\$4 or melt\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:05
L15	130	solder\$4 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (hold\$4 or maintain\$4 or tack\$4) adj7 (reflow\$4 or melt\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:46
L16	20	15 not 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 09:46
L17	1	solder\$4 and (((cure or cured or curing) near2 (adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy)) adj10 (hold\$4 or maintain\$4) adj7 (reflow\$4 or melt\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:07
L18	587	solder\$4 same (((cure or cured or curing) near2 (adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy)) with (reflow\$4 or melt\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 11:04
L20	503	solder\$4 same (((cure or cured or curing) near2 (adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy)) with (reflow\$4 or melt\$4) with solder\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:21
L21	28	20 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (top or above or edge or corner) adj10 solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/07/06 10:21
L22	38	11 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (attached or attaching or attaches or touch or touches or touching) adj10 solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:20
L23	24	11 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy) adj10 (attached or attaching or attaches or touch or touches or touching) adj5 solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:15
L24	28	20 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting or resin) adj10 (top or above or edge or corner) adj10 solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:29

, ,				-	0	2005/07/26 : 2 2
L25	684	solder\$4 same (((cure or cured or curing) near2 (adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting or resin)) with (reflow\$4 or melt\$4) with solder\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:21
L26	47	25 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting or resin) adj10 (top or above or edge or corner) adj10 solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:21
L27	19	26 not 24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:22
L28	684	solder\$4 same (((cure or cured or curing) near2 (adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting or resin)) with (reflow\$4 or melt\$4) with solder\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 11:04
L29	170	28 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting) with underfill\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:30
L30	151	28 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting) near5 underfill\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:31
L31	292	28 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting) near5 underfill\$3 or encapsulat\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:31
L32	220	28 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting) near5 (underfill\$3 or encapsulat\$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 11:14
L33	173	solder\$4 same (((cure or cured or curing) near2 (encapsulat\$4 or underfill\$4)) with (reflow\$4 or melt\$4) with solder\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:32
L34	129	33 and ((adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting) near5 (underfill\$3 or encapsulat\$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 10:32
L35	1389	228/49.1,49.5,50.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 11:03

L36	10263	(228/49.1,49.5,50,216,215.cds. or 361/751,767,768.cds. or 29/842,843.cds. or 257/737,738.cds. or 438/613-617.cds.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 11:04
L37	135	36 and (solder\$4 same (((cure or cured or curing) near3 (adhesive or thermoplastic or polymer\$5 or plastic\$4 or epoxy or thermoset or thermosetting or resin)) same ((reflow\$4 or melt\$4) with solder\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/06 11:05
L38	0	("6207475.pn.").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 11:14
L39	2	("6207475").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 11:14